ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES*	l Composition De ht 2005. IPC, Bannock al and Pan-American c	claration burn, Illinois. A opyright conver	Il rights reserved u ntions.	under both	This docume level parts, th	ent is a declaration en declaration	on of the substan ncompasses all lo	ces within the ma wer level materia	nufacturer list ls for which th	ed item. Note: i ne manufacture	if the item is an as r has engineering	ssembly with low responsibility.	
(5)_)				Form Type Distribute					s Materials and	ials and Mfg Information			
upplier Information													
ompany name*	Company unique ID			l	Unique ID Authority				Response Date*				
nsemi									2024-04-25				
Contact Name	Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA			Pro	Product-Env-Stewards@onsemi.com				
uthorized Representative*	Title - Repre	Title - Representative			Phone - Representative*			Ema	Email - Representative*				
roduct-Env-Stewards	Product Enviro Compliance				NA			Pro	Product-Env-Stewards@onsemi.com				
Requester Item Numbe	Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	Version	Manufacturing	Site	Weight*	UOM	Unit Type	
	MC78L	MC78L18ACPRAG ANA		NA 100MA 18V VREG		2024-04-25		CNF		198.01	mg	Each	
Ianufacturing Proccess I	nformation						-	-					
Terminal Plating / Grid	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020		L Rating	Peak Process Body Temperatur		ature Max Time	at Peak Temp	erature Numl	ber of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy NA		NA		0 C		30	se	conds 3			
omments													
or more information regarding	material composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl ohthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.2	mg	Supplier	Silicon (Si)	7440-21-3		3.2	mg
Die Attach	5.15	mg	Supplier	Silver (Ag)	7440-22-4		4.3775	mg
			Supplier	Phenolic Resin	Proprietary Data		0.7725	mg
Lead Frame	80.67	mg	Supplier	Silver (Ag)	7440-22-4		0.0081	mg
			Supplier	Iron (Fe)	7439-89-6		0.0807	mg
			Supplier	Copper (Cu)	7440-50-8		80.5571	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0242	mg
Mold Compound-Black	106.15	mg		Phenol Resin	proprietary data		10.615	mg
			Supplier	Carbon Black (C)	1333-86-4		1.0615	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		81.7355	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		12.738	mg
Plating	2.74	mg	Supplier	Tin (Sn)	7440-31-5		2.74	mg
Wire Bond - Au	0.1	mg	Supplier	Gold (Au)	7440-57-5		0.1	mg